



Product End-of-Life Disassembly Instructions

Product Category: Calculators

Marketing Name / Model

[List multiple models if applicable.]

HP Zbook 17 G4 Mobile Workstation

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	Power cords Adapters	2
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

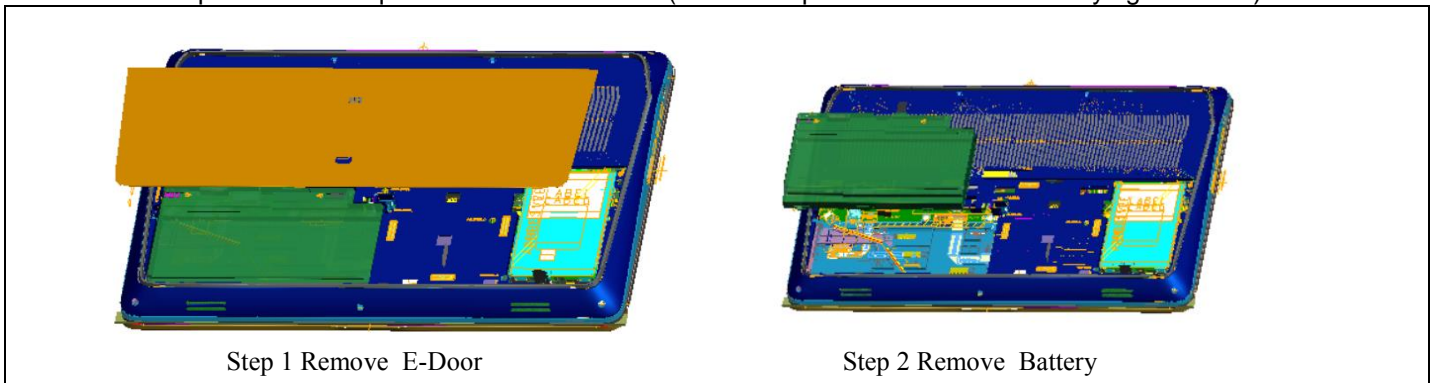
Tool Description	Tool Size (if applicable)
Screw Driver	T8
Screw Driver	No.1
Description #3	
Description #4	
Description #5	

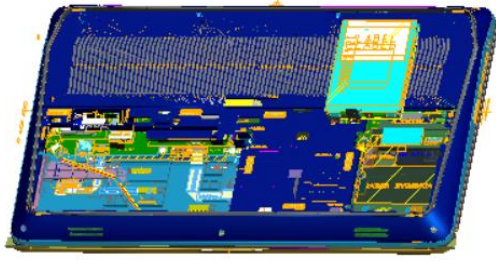
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

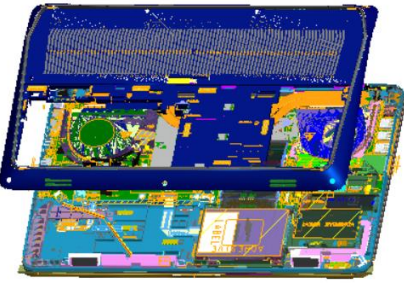
1. Remove E-Door
2. Remove Battery
3. Remove HDD
4. Remove D-Door
5. Remove SC Holder
6. Remove Internal Frame
7. Remove Smart Card Module
8. Remove TP Module
9. Remove Speaker
10. Remove LED PCB
11. Remove Keyboard
12. Remove Thermal Module
13. Remove MB
14. Remove Speaker
15. Remove Log Up
16. Remove Bezel
17. Remove Hinge
18. Remove Panel
19. Remove Web Camera
- 20.
- 21.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).





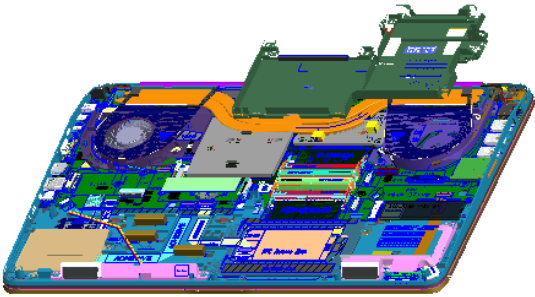
Step 3 Remove HDD



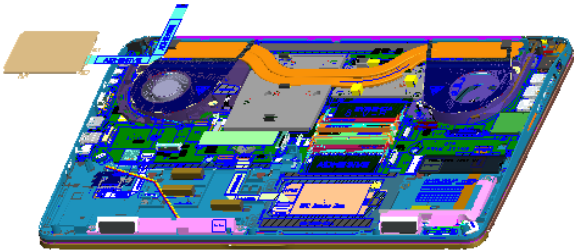
Step 4 Remove D-Door

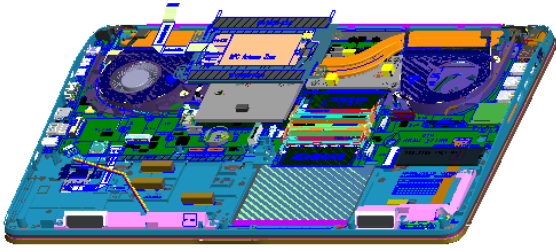


Step 5 Remove SC holder

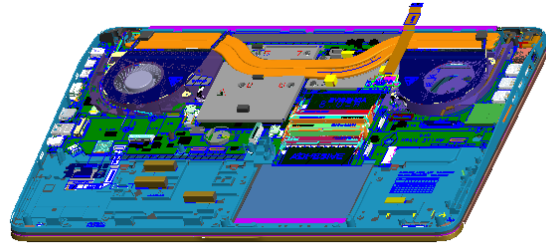


Step 6 Remove Internal Frame

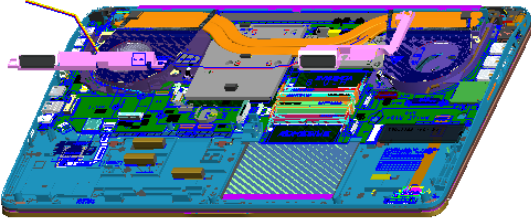




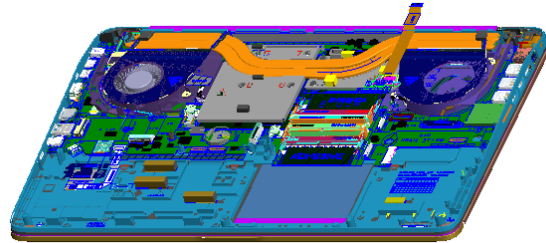
Step 7 Remove Smart Card Module



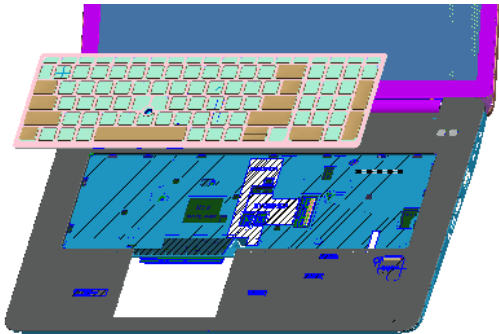
Step 8 Remove TP Module



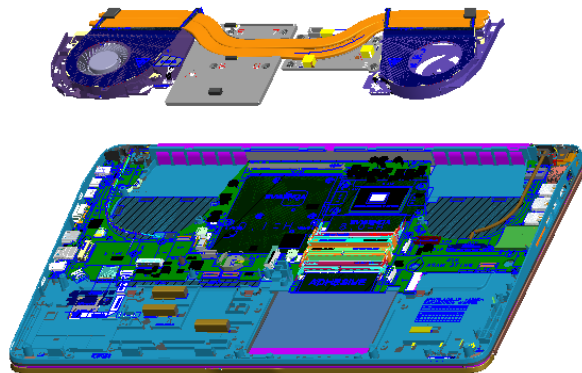
Step 9 Remove Speaker



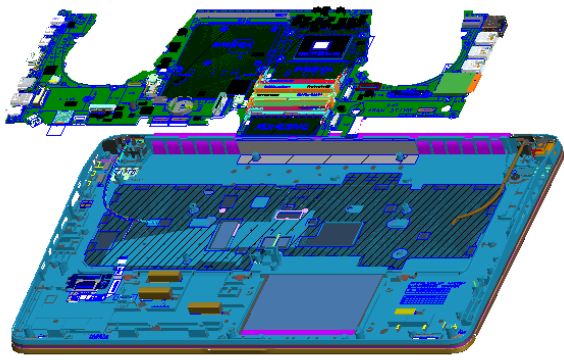
Step 10 Remove LED PCB



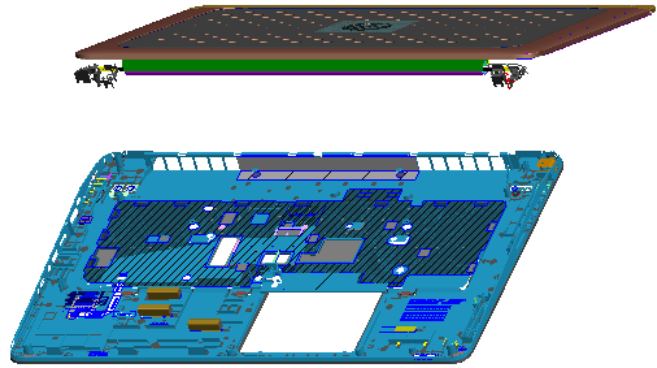
Step 11 Remove Keyboard



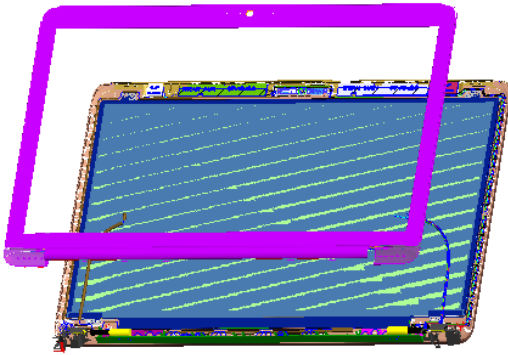
Step 12 Remove Thermal Module



Step 13 Remove MB



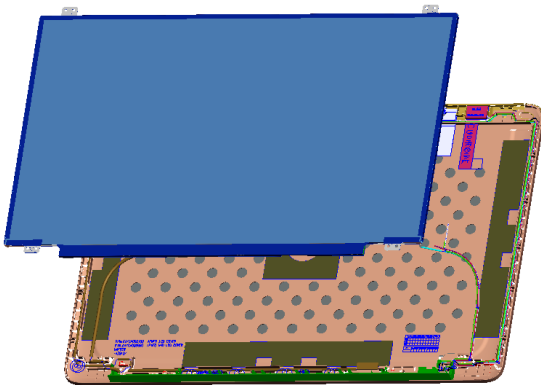
Step 14 Remove Log up



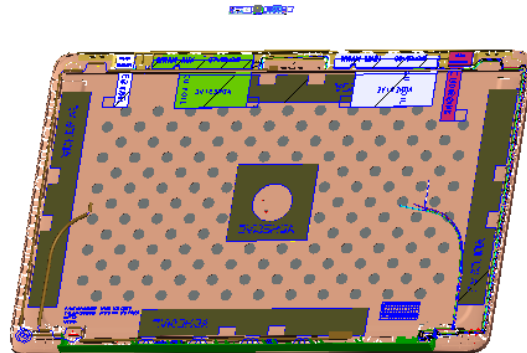
Step 15 Remove Bezel



Step 16 Remove Hinge



Step 17 Remove Panel



- 3.21 Total part disassembly
- 3.22 Remove battery module
- 3.23 Remove service door
- 3.24 LCD module set disassembly
- 3.25 Top case disassembly
- 3.26 Thermal module and mother board disassembly
- 3.27 Bottom case disassembly